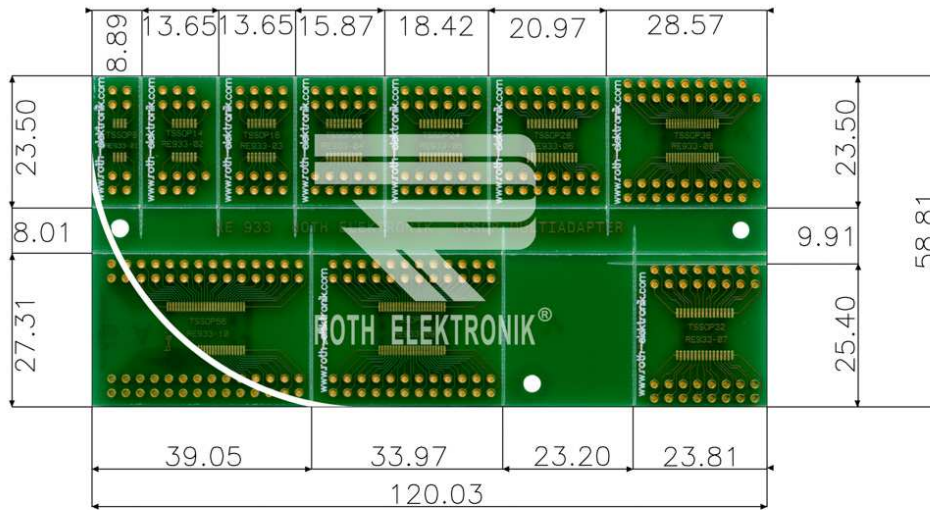


RE933

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for 10 different TSSOP's
- Pitch: 0.65 mm & 0.50 mm
- Hole diameter 1.00 mm
- Pre-scratched rated break point for the separation of individual modules from the board
- Size 58.90 x 120.10 mm

Module-No. Pitch mil Pin Size (mm)

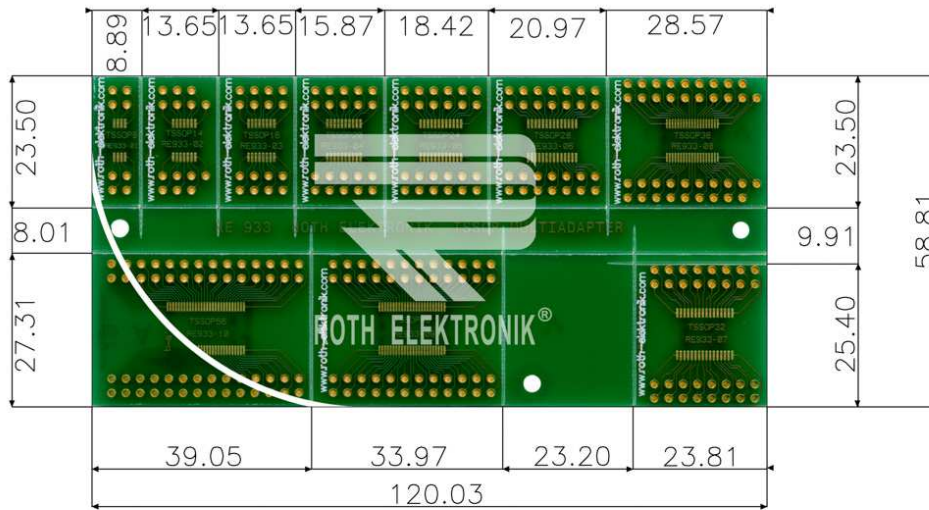
RE933-01 0.650 mm 22.5 8 4.400 (173 mil) RE933-02 0.650 mm 22.5 14 4.400 (173 mil) RE933-03 0.650 mm 22.5 16 4.400 (173 mil) RE933-04 0.650 mm 22.5 20 4.400 (173 mil) RE933-05 0.650 mm 22.5 24 4.400 (173 mil) RE933-06 0.650 mm 22.5 28 4.400 (173 mil) RE933-07 0.650 mm 22.5 32 4.400 (173 mil) RE933-08 0.500 mm 19.6 38 6.100 (240 mil) RE933-09 0.500 mm 19.6 48 6.100 (240 mil) RE933-10 0.500 mm 19.6 56 6.100 (240 mil)



RE933

- Epoxydglashartgewebe FR4 1,50 mm
 - Zweiseitig 35 µm Cu
 - Durchkontaktiert (PTH)
 - Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
 - Adaptionsplatine für 10 verschiedene TSSOP's
 - Pitch: 0,65 mm & 0,50 mm
 - Lochdurchmesser 1,00 mm
 - vorgeritzte Sollbruchstellen zum Trennen einzelner Module von der Platine
 - Größe 58,90 x 120,10 mm
- Modul-Nr. Pitch mil Pin Größe (mm)

RE933-01 0,650 mm 22,5 8 4,400 (173 mil) RE933-02 0,650 mm 22,5 14 4,400 (173 mil) RE933-03 0,650 mm 22,5 16 4,400 (173 mil) RE933-04 0,650 mm 22,5 20 4,400 (173 mil) RE933-05 0,650 mm 22,5 24 4,400 (173 mil) RE933-06 0,650 mm 22,5 28 4,400 (173 mil) RE933-07 0,650 mm 22,5 32 4,400 (173 mil) RE933-08 0,500 mm 19,6 38 6,100 (240 mil) RE933-09 0,500 mm 19,6 48 6,100 (240 mil) RE933-10 0,500 mm 19,6 56 6,100 (240 mil)

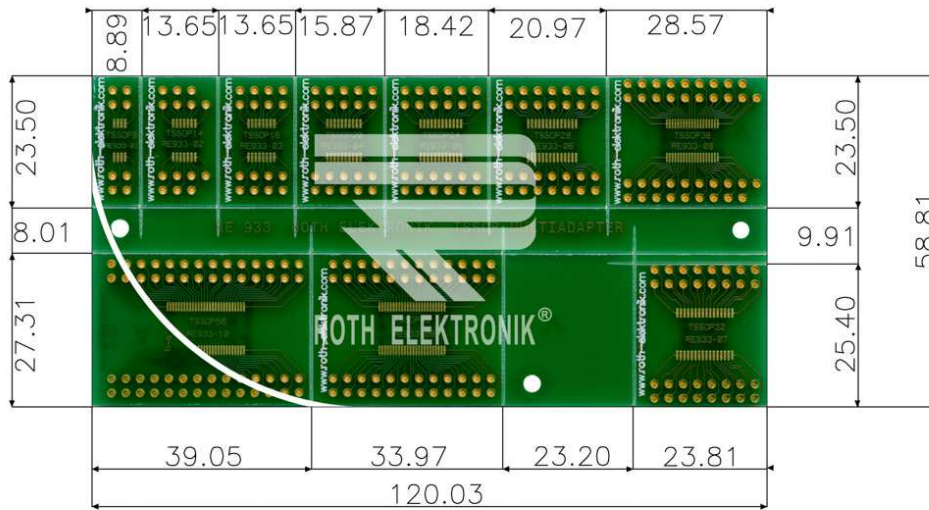


RE933

- Fibre de verre époxyde FR4 1,50 mm
- Double face 35 µm CU
- Métallisation des trous (PTH)
- Surface avec Ni/Au chimique et un laque d'arrêt de soudure
- Platine d'adaptation pour 10 TSSOP différents
- Pitch: 0,65 mm & 0,635 mm
- Perforation 1,00 mm Ø
- Points destinés à la rupture pour séparer des modules de la platine
- Dimensions 58,90 x 120,10 mm

Module-No. Pitch mil Pin Dimensions (mm)

RE933-01 0.650 mm 22,5 8 4,400 (173 mil) RE933-02 0.650 mm 22,5 14 4,400 (173 mil) RE933-03 0.650 mm 22,5 16 4,400 (173 mil) RE933-04 0.650 mm 22,5 20 4,400 (173 mil) RE933-05 0.650 mm 22,5 24 4,400 (173 mil) RE933-06 0.650 mm 22,5 28 4,400 (173 mil) RE933-07 0.650 mm 22,5 32 4,400 (173 mil) RE933-08 0.500 mm 19,6 38 6,100 (240 mil) RE933-09 0.500 mm 19,6 48 6,100 (240 mil) RE933-10 0.500 mm 19,6 56 6,100 (240 mil)



RE933

- Fibra de vidrio epoxídica FR4 1,50 mm
- Por dos lados 35 µm de Cu
- Agujeros con contactos metalizados (PTH)
- Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
- Adaptador para 10 TSSOP diferentes
- Pitch: 0,65 mm & 0,50 mm
- Diámetro de agujeros 1,00 mm
- Puntos de ruptura controlada prerrayados para separar módulos individuales de la placa de circuito impreso
- Tamaño 58,90 x 120,10 mm

Módulo-No. Pitch mil Pin Tamaño (mm)

RE933-01 0.650 mm 22.5 8 4.400 (173 mil) RE933-02 0.650 mm 22.5 14 4.400 (173 mil) RE933-03 0.650 mm 22.5 16 4.400 (173 mil) RE933-04 0.650 mm 22.5 20 4.400 (173 mil) RE933-05 0.650 mm 22.5 24 4.400 (173 mil) RE933-06 0.650 mm 22.5 28 4.400 (173 mil) RE933-07 0.650 mm 22.5 32 4.400 (173 mil) RE933-08 0.500 mm 19.6 38 6.100 (240 mil) RE933-09 0.500 mm 19.6 48 6.100 (240 mil) RE933-10 0.500 mm 19.6 56 6.100 (240 mil)